



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: **Katsumi Yamaguchi**  
Serial No.: **10/087,556**  
Filed: **03/01/2002**  
For: **Semiconductor Device and Bump Formation Method**

TI No.: **31471**  
Art Unit: **2811**  
Examiner: **Im, Junghwa M.**  
Conf. No.: **2191**

#11  
Notice of Appeal

McMillan  
8/4/03

NOTICE OF APPEAL

Commissioner For Patents  
Alexandria, VA 22313-1450

**MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)**

I hereby certify that the above correspondence is being deposited with the US Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450

*Elizabeth Austin*  
Elizabeth Austin  
Date 7/14/2003

RECEIVED  
JUL 29 2003  
TECHNOLOGY CENTER

Sir:

Applicant hereby appeals to the Board of Appeals from the decision dated June 6, 2003, of the Primary Examiner finally rejecting Claims 1-6 and 9-22.

Charge the fee of \$320.00 to the deposit account of Texas Instruments Incorporated, Account No. 20-0668. An original and two copies of this sheet are enclosed.

Texas Instruments Incorporated  
P. O. Box 655474, MS 3999  
Dallas, Texas 75265  
(972) 917-5653

Respectfully submitted,

*Michael K. Skrehot*

Michael K. Skrehot  
Attorney for Applicant  
Reg. No. 36,682